

IN THE CLAIMS:

Please amend the claims as follows:

1. (Currently Amended) An self-leveling method for clamping apparatus in a clamp for a leadframe in a wirebonding apparatus having a lower clamping surface for supporting a plurality of leadframes, the method comprising:  
providing an upper clamping member including a wirebonding window frame having a window therein movable under a clamping force for engaging portions of the plurality of leadframes, at least one leadframe of the plurality of leadframes located under the wirebonding window frame;  
providing self-leveling a resilient member located substantially above the upper clamping member; and  
contacting the upper clamping member for substantially causing the wirebonding window frame to engage the portions of the plurality of leadframes.
2. (Previously Presented) The self-leveling method of claim 1, wherein the upper clamping member comprises a member of a polymeric material.
3. (Previously Presented) The self-leveling method of claim 1, wherein the upper clamping member comprises a member of a polyimide material.
4. (Previously Presented) The self-leveling method of claim 1, wherein the resilient member comprises a polymeric material.
5. (Previously Presented) The self-leveling method of claim 1, wherein the resilient member comprises one of polytetrafluoroethylene material and urethane material.
6. (Previously Presented) The self-leveling method of claim 1, wherein a thickness of the resilient member comprises a range of approximately 0.005 to approximately 0.1 inch (approximately 0.0125 to 0.25 cm).

7. (Currently Amended) A self-leveling method for a self-adjusting clamping apparatus having a lower clamping surface supporting a leadframe in a leadframe clamp for connecting a semiconductor device to a leadframe in a wirebonding apparatus, the method comprising:  
providing an upper clamping member including a wirebonding window frame having a window therein movable under a clamping force to engage portions of at least one leadframe underlying the wirebonding window frame;  
providing a self-leveling resilient member located on one side of the upper clamping member;  
and  
contacting portions of the upper clamping member for substantially causing the wirebonding window frame to engage portions of the at least one leadframe located on one side of the wirebonding window frame.

8. (Previously Presented) The method of self-adjusting of claim 7, further comprising:  
providing a semiconductor device connected to the at least one leadframe; and  
connecting the portions of the at least one leadframe to portions of the semiconductor device.

9. (Previously Presented) The method of self-adjusting of claim 7, wherein the upper clamping member comprises a member of a polymeric material.

10. (Previously Presented) The method of self-adjusting of claim 7, wherein the upper clamping member comprises a member of a polyimide material.

11. (Previously Presented) The method of self-adjusting of claim 7, wherein the resilient member comprises a polymeric material.

12. (Previously Presented) The method of self-adjusting of claim 7, wherein the resilient member comprises one of polytetrafluoroethylene material and urethane material.

13. (Previously Presented) The method of self-adjusting of claim 7, wherein a thickness of the resilient member comprises a range of approximately 0.005 to approximately 0.1 inch (approximately 0.0125 to 0.25 cm).

14. (Currently Amended) An adjustable clamping apparatus in a leadframe clamp for clamping a portion of a leadframe in a leadframe strip, comprising:  
a lower clamping surface for supporting at least a portion of the leadframe;  
an upper clamping member comprising a wirebonding window frame having a window therein for movement when subjected to a force engaging portions of the leadframe; and  
a self-leveling resilient member located substantially above a portion of the upper clamping member, the resilient member compressible by the upper clamping member for substantially causing the wirebonding window frame to engage portions of the leadframe located under the wirebonding window frame.

15. (Currently Amended) The adjustable clamping apparatus of claim 1, wherein the upper clamping member is formed from one of a polymeric material-I, a polyimide material, a polytetrafluoroethylene material, and a urethane material.

16. (Original) The adjustable clamping apparatus of claim 1, wherein a thickness of the resilient member is approximately 0.005 to approximately 0.1 inch (approximately 0.0125 to 0.25 cm).

17. (Original) A leveling apparatus in a clamp for clamping a portion of a leadframe strip, comprising:  
apparatus for allowing movement of a clamp insert of the leveling apparatus relative to a clamp holder of the leveling apparatus;  
a resilient member located substantially above a portion of the clamp insert biasing the clamp insert against the leadframe; and

an apparatus for retaining the resilient member in a position for biasing the clamp insert against a portion of the leadframe strip.

18. (Original) The leveling apparatus of claim 4, wherein the resilient member includes a polymeric material having a substantially uniform thickness.

19. (Original) The leveling apparatus of claim 4, wherein the resilient member has a thickness of approximately 0.005 to approximately 0.1 inch (0.0125 to 0.25 cm).

20. (New) The leveling apparatus of claim 4, wherein the resilient member comprises one of a polymeric material, a polyimide material, polytetrafluoroethylene material, and a urethane material.

21. (Original) The leveling apparatus of claim 4, wherein the clamp insert includes an insert for movement in the range of approximately 0.0002 to approximately 0.01 inch (0.0005 to 0.05 cm) with respect to the resilient member for self-leveling of the clamp insert against a portion of the leadframe strip.

22. (Original) The leveling apparatus of claim 4, wherein the clamp insert comprises an electrically non-conductive material having a low heat conductivity.

23. (Currently Amended) A leveling apparatus in a clamp for clamping a portion of a leadframe strip, comprising:  
a lower clamping surface for supporting at least a portion of the leadframe strip;  
an upper clamping member having a peripheral wirebonding window frame for movement under a force for engaging portions of the leadframe strip underlying the peripheral wirebonding window frame; and  
a resilient member located substantially above a portion of the upper clamping member, ~~the a~~ polymeric member compressible by the upper clamping member for causing the peripheral wirebonding window frame to engage the portions of the leadframe strip.

24. (Original) The leveling apparatus of claim 10, wherein the upper clamping member includes one of a resilient polymeric material polyimide material, a polytetrafluoroethylene material, and a urethane material.

25. (Original) The leveling clamping apparatus of claim 10, wherein a thickness of the resilient material of the polymeric member is in the range of approximately 0.005 to approximately 0.1 inch (approximately 0.0125 to 0.25 cm).

26. (Original) A leveling apparatus for clamping portions of a leadframe strip, the leveling clamping apparatus comprising:  
apparatus for providing movement of a clamp insert of the leveling clamping apparatus relative to a clamp holder of the leveling clamping apparatus;  
a resilient polymeric member located substantially above a portion of the clamp insert for biasing the clamp insert against the leadframe; and  
a retaining apparatus for retaining the resilient polymeric member in a biasing position.

27. (Original) The leveling apparatus of claim 13, wherein the resilient polymeric member includes a polymeric material having a substantially uniform thickness.

28. (Original) The leveling apparatus of claim 13, wherein the polymeric material of the resilient polymeric member has a thickness in the range of approximately 0.005 to approximately 0.1 inch (0.0125 to 0.25 cm).

29. (Currently Amended) The leveling apparatus of claim 13, wherein the polymeric material of the resilient polymeric member comprises one of a ~~a~~-polymeric material, a polyimide material, a polytetrafluoroethylene material, and a urethane material.

30. (Original) The leveling clamping apparatus of claim 13, wherein the clamp insert includes an insert for movement of approximately 0.0002 to approximately 0.01 inch (0.0005 to

0.05 cm) against the resilient polymeric member for leveling of the clamp insert against the leadframe strip.

31. (Original) The leveling apparatus of claim 13, wherein the clamp insert comprises an electrically non-conductive material with low heat conductivity.